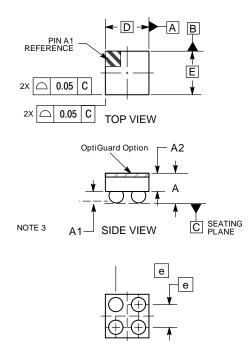


WLCSP4, 0.96x0.96 CASE 567AW ISSUE O

## DATE 26 JUL 2010

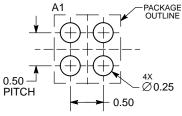


BOTTOM VIEW

NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

(	CROWNS OF SOLDER B				
		MILLIMETERS			
	DIM	MIN	MAX		
	Α	0.56	0.72		
	A1	0.21	0.27		
	A2	0.42 REF			
	b	0.29	0.35		
	D	0.96 BSC			
	Е	0.96	BSC		
	e	0.50	BSC		

RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb–Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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